



Advances in Multiscale and Multifield Solid Material Interfaces

Guest Editors:

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Deadline for manuscript
submissions:

closed (31 December 2021)

Message from the Guest Editors

Dear Colleagues,

This Special Issue is dedicated to recent advances in fundamental and applications of solid material interfaces. Contributions concerning theoretical, numerical and experimental aspects are welcome from scientists working in different fields of material science and mechanics of materials.

Topics to be covered include, but are not limited to, the following:

- multi-scale modeling of interphases, thin films and surfaces, contact laws;
- models of imperfect, sliding, debonding or cohesive interfaces in composite materials;
- deformation, damage, fracture and other dissipative processes at interfaces;
- advanced finite element methods for the computational modeling of interfaces and surfaces;
- molecular dynamics simulations for interface design;
- recent developments of adhesive technology and materials.

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Guest Editors





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Message from the Editor-in-Chief

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